



iDICs

ICECM/iDICs 2026 JOINT CONFERENCE

NOVEMBER 02-05, 2026

HO CHI MINH CITY, VIETNAM



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Financial Sponsors

HCM-UTE
Correlated Solutions, Inc
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Venue and Accommodation

Caravelle Saigon Hotel
19-23 Lam Son Square, Sai Gon Ward, Ho Chi Minh City, Vietnam

Additional Information

Visa applications: <https://evisa.gov.vn>

Contact

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Welcome to ICECM/iDICs 2026 Joint Conference, which will be held at Caravelle Saigon Hotel, Ho Chi Minh City, Vietnam, on November 02-05, 2026.

ICECM 2026: International Conference on Experimental and Computational Mechanics 2026

The International Conference on Experimental and Computational Mechanics 2026 (ICECM 2026) is jointly hosted by Ho Chi Minh City University of Technology and Engineering (HCM-UTE), and the Asian Society for Experimental Mechanics (ASEM). The conference aims to provide a high-level international forum for researchers, academics, and practitioners to exchange knowledge and share recent advances, innovative methodologies, and practical applications in the fields of computational and experimental mechanics

iDICs 2026: International Digital Image Correlation Society Annual Meeting 2026

The International Digital Image Correlation Society Annual Meeting 2026 (iDICs 2026) is a leading international forum for researchers, engineers, and practitioners working in the field of digital image correlation (DIC) and full-field optical measurement techniques. The conference is organized by the International Digital Image Correlation Society (iDICs) in collaboration with Ho Chi Minh City University of Technology and Engineering (HCM-UTE). iDICs 2026 aims to provide a platform for presenting cutting-edge research, innovative methodologies, and practical applications of DIC, while fostering knowledge exchange and collaboration among experts from academia, industry, and research institutions worldwide.

The joint conference invites the submission of one-page extended abstracts presenting ongoing research, recent results, or practical applications related to experimental and computational mechanics, digital image correlation, and full-field optical measurement techniques.

We particularly encourage submissions that focus on the following topics (but are not limited to):

- (1) Advanced Mechatronic and Control Systems
- (2) Advanced Mechatronic Systems
- (3) Artificial Intelligence and Advanced Computational Methods in Experimental Mechanics
- (4) Artificial Intelligence and Machine Learning in Mechatronics
- (5) DIC Algorithms and Computational Methods
- (6) DIC and other Optical Techniques in Experimental Mechanics
- (7) DIC for Advanced Manufacturing Monitoring
- (8) DIC in Materials Testing and Constitutive Model Calibration
- (9) DIC Standardization and Uncertainty Quantification
- (10) Digital Volume Correlation
- (11) Experimental and Computational Fluid Mechanics
- (12) Experimental and Computational Mechanics for Dynamic Response and Extreme Environmental Conditions
- (13) Experimental and Computational Mechanics for Manufacturing and Material Behavior Analysis
- (14) Experimental and Computational Mechanics for Material Characterization and Structural Mechanics Analysis
- (15) Experimental and Computational Mechanics for Semiconductor Technology
- (16) Experimental and Computational Mechanics in Biomechanics Application
- (17) Experimental and Computational Multiscale Methodologies
- (18) Global and Adaptive DIC Methods
- (19) High-speed DIC and Modal Analysis
- (20) Mechatronics and Control System
- (21) Microscale Measurements with DIC
- (22) Modern and Sustainable Industrial Engineering and Management
- (23) Novel Imaging Modalities

Paper submission

All submissions must be in English. The one-page extended abstracts are to be submitted electronically in PDF format via the CMT submission link: <https://cmt3.research.microsoft.com/ICECMiDICs2026>.

Important dates

Proposal for special session	April 30, 2026
Special session acceptance notification	May 07, 2026
Abstract submission deadline	June 20, 2026
Abstract acceptance notification	June 30, 2026
Early-bird registration & payment ends	July 31, 2026
Registration & payment deadline	August 30, 2026
Letter of invitation delivery	October 01, 2026

Training courses (November 02, 2026)

The iDICs will offer several of its most popular training courses at Ho Chi Minh City University of Technology and Engineering (HCM-UTE) before ICECM/iDICs 2026 Joint Conference:

DIC101 – Learn the Good Practices Guide (GPG) and prepare for Level 1 Certification (full day).

How to Pattern...Everything – Learn how to pattern for DIC at multiple scales (½ day).

Measurement Uncertainty – Learn the approved methods of assessing the accuracy of your DIC measurement (½ day).

Registration fees

Category	Early-bird rate (before August 01, 2026)	Standard rate (from August 01, 2026)
Regular author registration	500 USD	600 USD
Student registration [Note]: The student must be the first author and the presenter of the abstract	250 USD	300 USD
Training course registration	100 USD	100 USD

Sponsorship opportunities

ICECM/iDICs 2026 sponsorships at the Bronze through Gold level will include acknowledgement in the printed conference program, during various sessions, and the listed items offered at the different sponsorship levels. For more details, please visit [HERE](#).